LNJ352W83RA

Hight Bright Surface Mounting Chip LED

SV (Side View) -0.4 Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	55	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Lighting Color

• Yellow Green

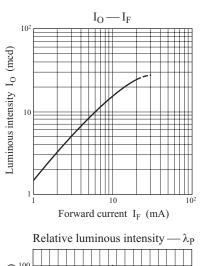
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

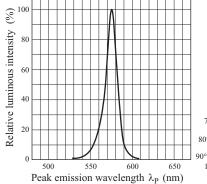
Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I _O	$I_F = 5 \text{ mA}$	4.0	8.5	33.4	mcd
Reverse current	I _R	$V_R = 4 V$			100	μA
Forward voltage	V _F	$I_F = 5 \text{ mA}$		1.95	2.30	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_F = 5 \text{ mA}$		575		nm
Dominant emission wavelength *2	λ _d	$I_F = 5 \text{ mA}$	566	572	578	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		20		nm

Note) *1: Measurement tolerance: ±20%

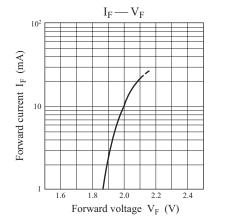
*2: Measurement tolerance: ±3 nm

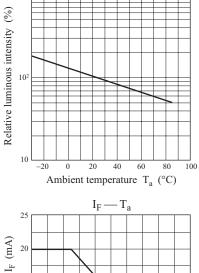




70

100

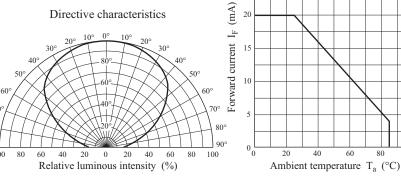




Relative luminous intensity

10

Ta



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100

60

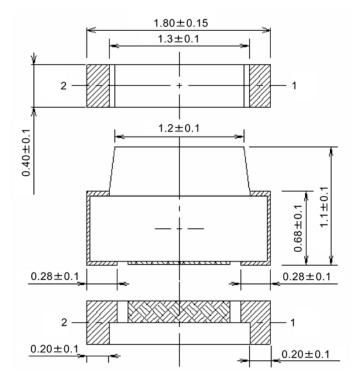
80

20

40

Package (Unit: mm)

KLTFSN2K5200



- Pin name
 - 1: Anode
 - 2: Cathode

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